

**Amendments to the Claims:**

The following listing of claims replaces all other versions of claims previously presented.

**Listing of Claims:**

Claims 1-9 (Cancelled)

Claim 10 (Previously Presented): A semiconductor device, comprising:

a circuit board;

a first semiconductor chip positioned on the circuit board;

a second semiconductor chip positioned on the first semiconductor chip; wherein

(a) the circuit board has a first pad, a second pad spaced away from the first pad in a direction along an outer periphery of the first semiconductor chip, and a wire connecting between the first pad and the second pad on a surface of the circuit board supporting the first semiconductor chip, the wire being printed on the circuit board together with the first and second pads, and the wire extending along the outer periphery of the first semiconductor chip between the first and second pads;

(b) the second semiconductor chip has a third pad positioned adjacent to the second pad but away from the first pad on the circuit board; and

(c) the second pad on the circuit board and the third pad on the second semiconductor chip are electrically connected through a bonding wire, so that the third pad on the second semiconductor chip is electrically connected with the first pad on the circuit board through the bonding wire, the second pad on the circuit board, and the wire on the circuit board.

Claims 11-12 (Cancelled)

Claim 13 (Previously Presented): The semiconductor device according to claim 10, wherein the semiconductor device is mounted on a motherboard.

Claim 14 (Previously Presented): The semiconductor device according to claim 10, wherein the circuit board further comprises a fourth pad positioned adjacent the outer periphery of the first semiconductor chip.

Claim 15 (Previously Presented): The semiconductor device according to claim 10, wherein the first semiconductor chip has a fifth pad positioned adjacent the outer periphery of the first semiconductor chip.

Claim 16 (Previously Presented): The semiconductor device according to claim 10, wherein the second semiconductor chip has a sixth pad positioned adjacent the outer periphery of the second semiconductor chip.

Claim 17 (Previously Presented): A semiconductor device, comprising:

- a circuit board;
- a first semiconductor chip positioned on the circuit board;
- a second semiconductor chip positioned on the first semiconductor chip; wherein
  - (a) the circuit board has a first pad, a second pad spaced away from the first pad in a direction along an outer periphery of the first semiconductor chip;
  - (b) the first semiconductor chip has a third pad, a fourth pad spaced away from the third pad in a direction along an outer periphery of the second semiconductor chip, the third and fourth pads being positioned adjacent to the first and second pads, respectively, and a wire electrically connecting between the third pad and the fourth pad on a surface of the first semiconductor chip supporting the second semiconductor chip, the wire being printed on the first semiconductor chip together with the third and fourth pads, and the wire extending along the outer periphery of the second semiconductor chip between the third and fourth pads;

(c) the second semiconductor chip has a fifth pad positioned adjacent to the third pad but away from the fourth pad on the first semiconductor chip; and

(d) the first pad on the circuit board and the third pad on the first semiconductor chip, the first pad on the circuit board and the fifth pad on the second semiconductor chip, and the second pad on the circuit board and the fourth pad on the first semiconductor chip are electrically connected through respective bonding wires.

Claim 18 (Previously Presented): The semiconductor device according to claim 17, wherein the semiconductor device is mounted on a motherboard.

Claim 19 (Previously Presented): A semiconductor device, comprising:

a circuit board;

a first semiconductor chip positioned on the circuit board;

a second semiconductor chip positioned on the first semiconductor chip; wherein

(a) the circuit board has a first pad and a second pad spaced away from the first pad in a direction along an outer periphery of the first semiconductor chip;

(b) the second semiconductor chip has a third pad positioned adjacent to the second pad but away from the first pad on the circuit board; and

(c) the first and second pads on the circuit board and the second pad on the circuit board and the third pad on the second semiconductor chip are electrically connected through respective bonding wires.

Claim 20 (Previously Presented): The semiconductor device according to claim 19, wherein the first semiconductor chip has a sixth pad positioned adjacent the outer periphery of the first semiconductor chip.

Claim 21 (Previously Presented): The semiconductor device according to claim 19, wherein the semiconductor device is mounted on a motherboard.

Claim 22 (Currently Amended): A semiconductor device, comprising:  
a first semiconductor chip having a first pad;  
a second semiconductor chip having a second pad, a third pad and a connecting wire electrically connecting the second pad with the third pad;  
a circuit board having a fourth pad;  
a first bonding wire connecting the first pad and the second pad;  
a second bonding wire connecting the third pad and the fourth pad,  
wherein the connecting wire is formed in the second semiconductor chip,  
the second pad is formed on a top surface of the second semiconductor chip, beside its one edge, and  
the third pad is formed on a top surface of the second semiconductor chip, beside its another edge, and  
the fourth pad is formed adjacent an outer periphery of said another edge.

Claim 23 (New): A semiconductor device, comprising:  
a first semiconductor chip having a first pad;  
a second semiconductor chip having a second pad, a third pad and a connecting wire electrically connecting the second pad with the third pad;  
a circuit board having a fourth pad;  
a first bonding wire connecting the first pad and the second pad;  
a second bonding wire connecting the third pad and the fourth pad,

wherein the connecting wire is formed in the second semiconductor chip, spaced apart from a top surface of the second semiconductor chip,

the second pad is formed on the top surface of the second semiconductor chip, beside its one edge, and

the third pad is formed on the top surface of the second semiconductor chip, beside its another edge.